Electronic Acknowledgement Receipt FES ID: 1094697 Application Number: 10651813 Confirmation Number: 9556 Title of Invention: Semiconductor chip having bond pads and multi-chip package First Named Inventor: Young-Hee Song Customer Number: 20575 Filer: Alexander Charles Johnson/Li Mei Vermilya Filer Authorized By: Alexander Charles Johnson Attorney Docket Number: 9903-078 Receipt Date: 27-JUN-2006 Filing Date: 28-AUG-2003 Time Stamp: 20:42:20 Application Type: Utility International Application Number: Payment information:

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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1		9903078g.pdf	658879	yes	12

	Multipart Description				
	Doc Desc	Start	End		
	Miscellaneous Incoming Letter	1	1		
	Amendment - After Non-Final Rejection	2	9		
	Applicant Arguments/Remarks Made in an Amendment	10	12		
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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.